

ABSTRACT OF THE DISCLOSURE

A wiring transfer sheet including a carrier base and a wiring layer formed thereon is produced so that an exposed area of a surface of the carrier base on which the wiring layer is formed has a plurality of concavities. By transferring the wiring layer to an electrically insulating substrate with this wiring transfer sheet, convexities which are complementary to the concavities are formed on the electrically insulating substrate. The convexities improve adhesion between a wiring board and a resin stacked thereon. Therefore, the wiring board thus obtained has surface coplanarity suitable for mounting a semiconductor bare chip and an electronic component as a whole, and a microscopical surface structure which adheres to a material stacked thereon.